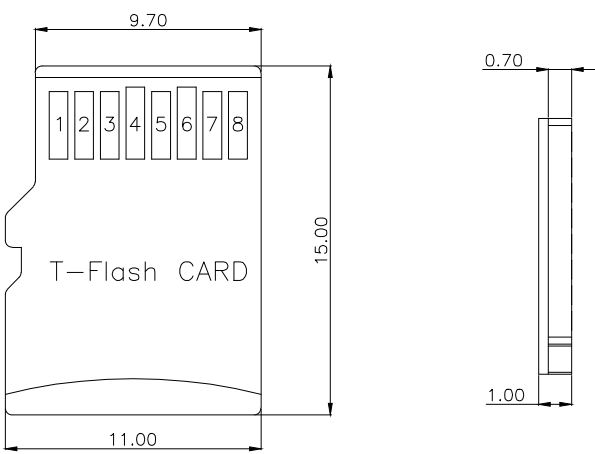
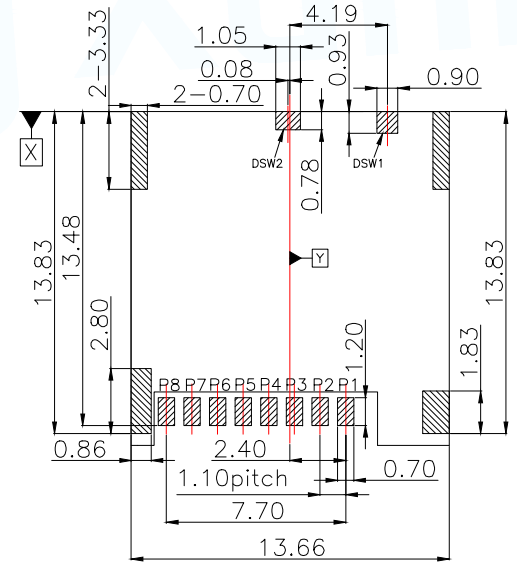
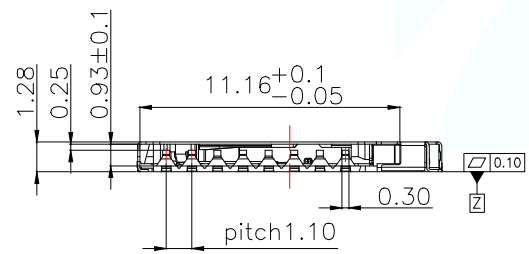


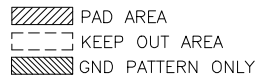
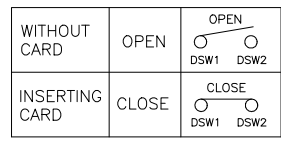
Specification

- 1.MATERIAL:
- 1.1 Insulator:High Temperature Thermoplastic, LCP SZ6505HF black UL94V-0.
 - 1.2 Terminal: Phosphor Bronze(C5210-H, T=0.15mm)
 - 1.3 Shell: SUS301-3/4H T=0.10mm
 - 1.4 Spring: SUS301 L=9.80mm
 - 1.5 Slider: PPA black
 - 1.6 Drawbar: SUS304-H,L=3.85mm
- 2.Plating:
- 2.1 Terminal: Plated 80u"min Ni Overall
Plated 1u"min Au Selective contact area
Plated 1u"min AU over Ni on solder area
 - 2.2 Shell: Plated 1u"min AU overll 50u"min Ni
- 3.Property:
- 3.1 Current Rating :0.5A AC/DC max.
 - 3.2 Voltage Rating :12V AC/DC
 - 3.3 Ambient Temperature Range :-20°C~+60°C
 - 3.4 Ambient Humidity Range :95% R.H. Max.
 - 3.5 Contact Resistance:100mΩ max.
 - 3.6 Insulation Resistance:1000MΩ min./500VDC
 - 3.7 Durability:5000 cycles

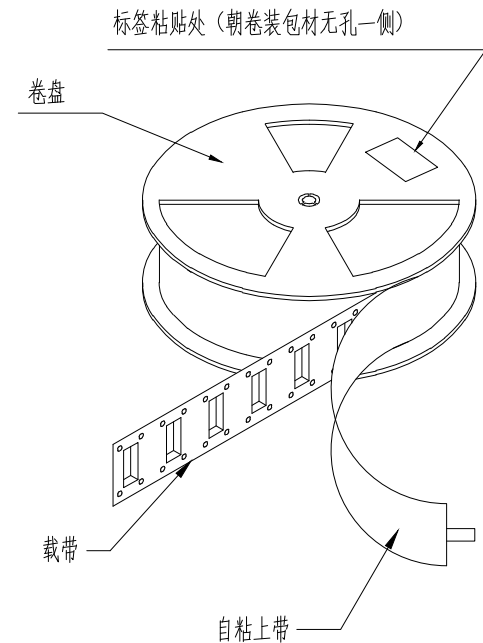
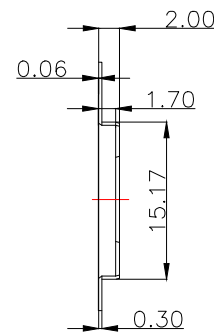
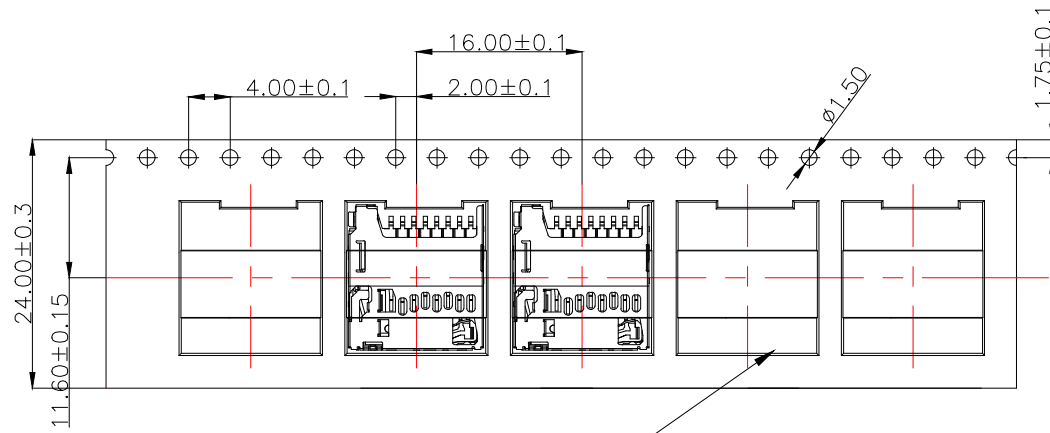


TF CARD PIN DEFINE			
PIN NO.	NAME	TYPE	DESCRIPTION
1	DAT2	I/O/PP	DATE LINE(BIT2)
2	CD/DAT3	I/O/PP	CARD DETECT DATE LIN(BIT3)
3	CMD	PP	COMMAND RESPONSE
4	VDD	S	SUPPLY VOLTAGE
5	CLK	I	CLOCK
6	VSS	S	SUPPLY VOLTAGE GROUND
7	DATO	I/O/PP	DATE LINE(BIT0)
8	DAT1	I/O/PP	DATE LINE(DIT1)

Circuit Diagram for Detect Switch

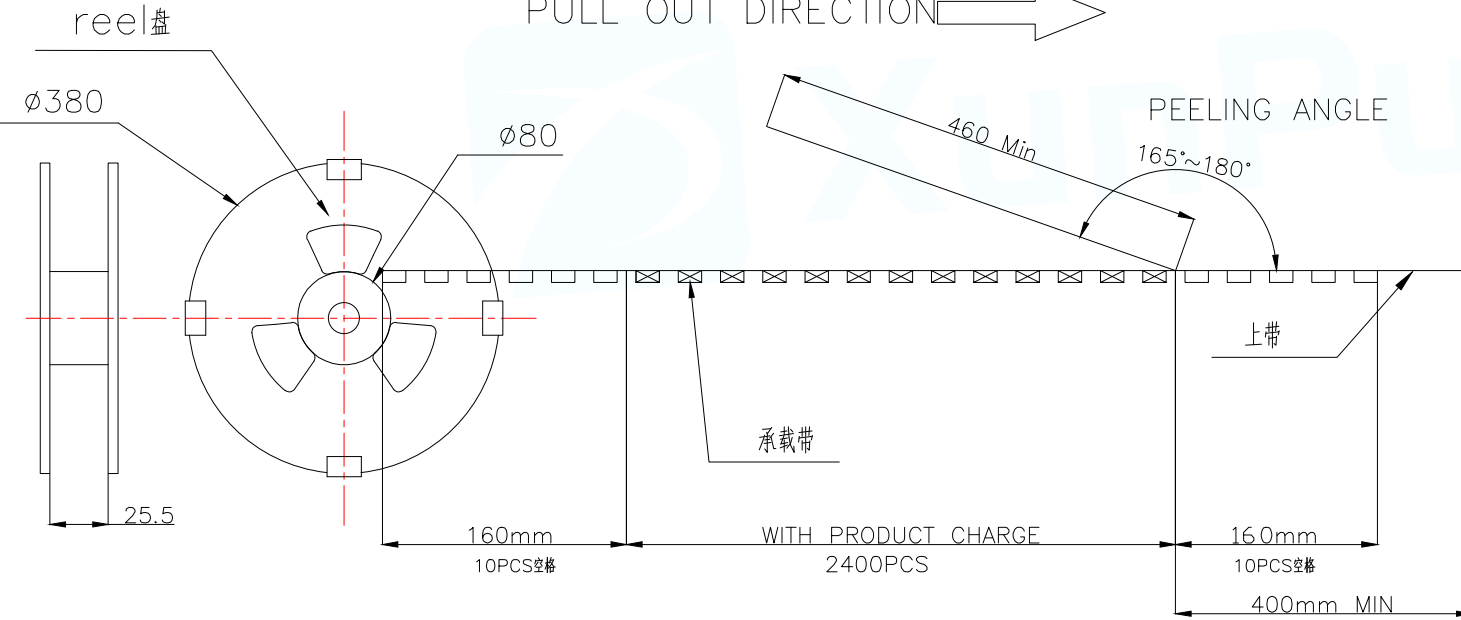


MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: Micro SD push push 1.28H
DECIMALS:	ANGLES:		PAR TF-108-ARP10
.X:±0.35	X.':±2'		DWN
.XX:±0.20	X.X':±1"		CHKD
.XXX:±0.10	X.XX':±0.5'	APVD	SCALE:1:1 UNIT:MM
CUSTOMER COPY		SIZE:A4	UNIT:MM
		SHEET:1F1	REV:A



产品放置方向

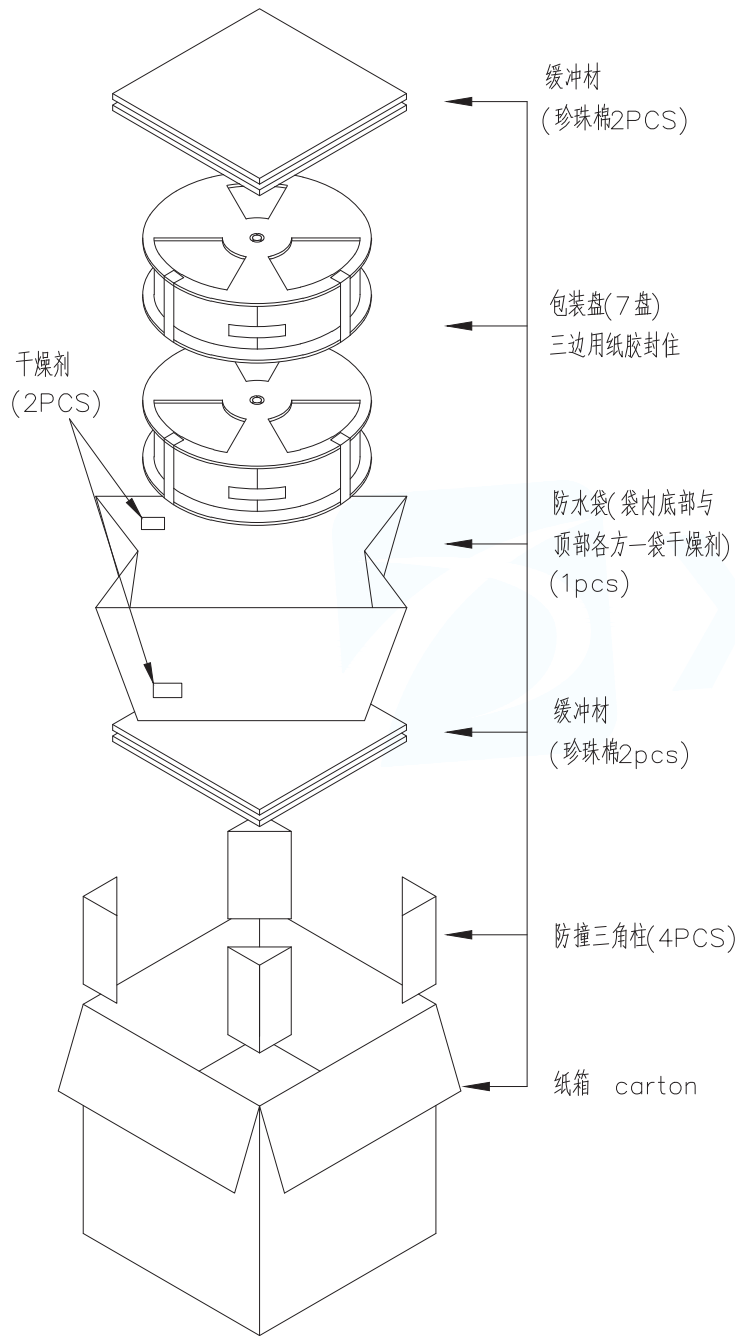
PULL OUT DIRECTION



PACKING INFORMATION

PART NAME	Micro SD H1.28 CARD包装规范
QUANTITY OF PER TRAY	2400PCS/TRAY
QUANTITY OF PER CARTON	7*2400=16800PCS/CARTON

MANUFACTURE DWG				
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: Micro SD push push 1.28H	
DECIMALS:	ANGLES:		PAR	TF-108-ARP10
.X:±0.35	X.°:±2'		DWN	
.XX:±0.20	X.X':±1"		CHKD	
.XXX:±0.10	X.XX':±0.5'		APVD	
		CUSTOMER COPY	SIZE:A4	UNIT:MM
			SHEET:1F1	REV:A



10	干燥剂	2PCS
9	三角压线条	4PCS
8	珍珠棉	4PCS
7	纸箱	1PCS
6	保护带	7PCS
5	自粘上带	38.72M*7
4	卷盘	7PCS
3	PE防水袋	1PCS
2	载带	7pcs
1	Micro SD H1.28 CARD	16800PCS

备注:

1. 每卷载带前后各留 10 个空格不使用.
2. 每卷载带包装2400PCS产品.
3. 以自粘上带覆盖经包装机冷封包装.
4. 以保护带覆盖于外圈再以胶带固定并粘贴卷盘标签.
5. 将 7 卷包装好的产品放入PE防水袋,
防水袋的上下各放置 2PCS珍珠棉,以胶带固定PE防水袋.
6. 将包装好的 7 卷产品放入纸箱,四周用三角压线条固定;
外箱用胶带呈“工”字形封口.
7. 外箱标签的贴法请参照客户资料.

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: Micro SD push push 1.28H
			PAR TF-108-ARP10
DECIMALS:	ANGLES:		DWN
.X: ±0.25	X.: ±2°		CHKD
.XX: ±0.15	X.X: ±1°		APVD
.XXX: ±0.05	X.XX: ±0.5°	CUSTOMER COPY	SCALE: 1:1
		COPY	UNIT: MM
			SIZE: A4
			SHEET: 1F1
			REV: A

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [Memory Card Connectors](#) category:

Click to view products by [XUNPU](#) manufacturer:

Other Similar products are found below :

[M21-033321-005](#) [6407-249V-25273P](#) [6407-249V-25343P](#) [6426-201-21343](#) [69.920.0553.0](#) [MCR60A-98D-2.54DSA\(70\)](#) [809180410000000](#)
[DM3AT-SF-PEJM5\(41\)](#) [IC11S-BUR-PNEJL\(71\)](#) [252-0144-000](#) [2041353-2](#) [308-DS1P0811-192](#) [HM2P09PDR360N9LF](#) [10014744-011TLF](#)
[11327-001](#) [11327-002](#) [617230001](#) [NX1-32T-KT3K\(05\)](#) [N7E50-U516RB-50-SIN0005](#) [68-580163-21S](#) [125A-78C00](#) [CCM03-3109 B LFT](#)
[2309923-1](#) [61126-050CAHLF](#) [IC1GA-68PD-1.27DS-EJ\(72\)](#) [GTFP08432B1HR](#) [SCE2MSDZN76A121SN](#) [10014744-011ALF](#) [10014744-](#)
[011LF](#) [10057542-1211FLF](#) [10067972-000LF](#) [10067972-050LF](#) [10122302-20110LF](#) [G85D1162022HHR](#) [MUP-C7809-1](#) [NANO SIM 7P](#)
[H1.37](#) [MICRO SIM 7P H1.35](#) [TF-CARD H1.8 SY](#) [MICRO SIM 6P H1.35](#) [TF-CARD H1.8](#) [TF-115Y-BCP9](#) [TF-115YY-ACP9](#) [SMN-309-](#)
[ARP6](#) [TF-115Y-ACP9](#) [TF-108-ARP10](#) [SMN-303S-ACP7](#) [SNO-14100](#) [SD-112S](#) [MUP-C7804-1](#) [KH-TF-07DT](#)